

[***BUMP MANUFACTURING METHOD***]

Abstract of Disclosure

A method of forming bumps on the active surface of a silicon wafer. A first under-ball metallic layer is formed over the active surface of the wafer. A second under-ball metallic layer is formed over the first under-ball metallic layer. A portion of the second under-ball metallic layer is removed to expose the first under-ball metallic layer. A plurality of solder blocks is implanted over the second under-ball metallic layer. A reflux operation is conducted and then the exposed first under-ball metallic layer is removed so that only the first under-ball metallic layer underneath the second under-ball metallic layer remains.

Figures

Figure 1: A line graph showing the relationship between the number of hours spent studying and the score on a test. The x-axis represents 'Hours Studied' (0 to 10) and the y-axis represents 'Test Score' (0 to 100). The data points are as follows:

Hours Studied	Test Score
0	50
1	55
2	60
3	65
4	70
5	75
6	80
7	85
8	90
9	95
10	100

The graph shows a positive linear correlation between the number of hours studied and the test score. The line starts at (0, 50) and ends at (10, 100), with a constant slope of 10 points per hour.